

Quarterly Reliability Monitoring Results

Quarters: Q1/2021 to Q4/2021

Based on structural similarity

Supplier		User Part Number				
Nexperia B.V.		PDTC123YM				
Name of Laboratory		Part Description				
Assembly reliability labs		Nexperia DHAM MCD package Small Signal Bipolar Transistor				
Based on AEC-Q101 Test		Test Conditions	Duration	# Lots	# Quantity	# Rejects
# E1	TEST Pre- and Post-Stress Electrical Test	Tamb = 25 °C	N/A	see below	all parts	see below
# A1	PC Preconditioning	JESD22-A113 Bake Tamb = 125 °C Soak Tamb = 85 °C, RH = 85% Reflow soldering	24 hours 168 hours 3 cycles	208	16640	0
# B1	HTRB High Temperature Reverse Bias	MIL-STD-750-1 M1039 Method A Tj = Tjmax, Vr = 100% of max. datasheet reverse voltage	1000 hours	202	16160	0
# A4	TC Temperature Cycling	JESD22-A104 -65 °C to Tjmax, not to exceed 150°C	1000 cycles	52	4160	0
# A3 alt	AC Autoclave	JESD22-A102 Tamb = 121 °C, RH = 100 % Pressure = 205 kPa (29.7 psia)	96 hours	52	4160	0
# A2 alt	H3TRB High Humidity High Temperature Reverse Bias	JESD22-A101 Tamb = 85 °C, RH = 85%, VR = 80 % of rated reverse voltage ^[1]	1000 hours	52	4160	0
# A5	IOL Intermittent Operating Life	MIL-STD-750 Method 1037 ton = toff, devices powered to insure ΔTj = 100 °C for 15000 cycles	1000 hours	52	4160	0
# C8	RSH Resistance to Solder Heat	JESD22-A111 260 °C ± 5 °C	10 s	n.a.	n.a.	n.a.
# C10	SD Solderability	J-STD-002		111	1110	0

[1] The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

Calculation of FIT and MTF

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test #B1)

Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

Wafer Fab	Technology	Quantity	Rejects	Failure Rate (FIT)	MTTF (hrs)
Nexperia DHAM	Small Signal Bipolar Transistor	16160	0	0.26	3.81E+09

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